FSL

PRODUCT AND PROCESS CHANGE NOTIFICATION

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ISSUE DATE: 28-May-2014
NOTIFICATION: 16283
TITLE: MC33926PNB PQFN Cold Temperature Test Elimination
EFFECTIVE DATE: 24-Nov-2014

DEVICE(S)

MPN
MC33926PNB
MC33926PNBR2

AFFECTED CHANGE CATEGORIES

- TEST PROCESS

DESCRIPTION OF CHANGE

Freescale Semiconductor announces the cold temperature test insertion elimination from the Final Test production flow of the MC33926PNB devices associated with this notification.
Cold test is covered by the remaining production test flow insertions.
This evaluation has been successfully completed according to Freescale specifications.

Current Test Flow:
Room Temp Probe -> Hot Temp Test ->Cold Temp Test

Proposed Test Flow:
Room Temp Probe -> Hot Temp Test

REASON FOR CHANGE

Improve capacity for optimized cycle time and delivery.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

There is no impact to device Form, Fit, Function or Reliability.

According to JEDEC Standard JESD46, lack of acknowledgement of this PCN within 30 days will be considered acceptance of change. To request further data or inquire about the notification, please enter a **Service Request.**

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 11-Apr-2014

QUALIFICATION STATUS: COMPLETED

QUALIFICATION PLAN:

Freescale Semiconductor standard specification for Test Elimination was followed for this change. See attached Qualification Report.

RELIABILITY DATA SUMMARY:

NA

ELECTRICAL CHARACTERISTIC SUMMARY:

NA

CHANGED PART IDENTIFICATION:

No change to orderable part number.

ATTACHMENT(S):

External attachment(s) FOR this notification can be viewed AT:
16283_MC33926PNB_Cold_Test_Elimination_Qualification_Report_GPCN.pdf